AMENDMENTS TO THE CLAIMS:

The following listing of the claims replaces all prior versions, and listings, of the claims in the application:

1. (Currently Amended) A copper-clad laminate comprising a polyimide film and an electrolytically plated copper film placed on at least one surface side of the polyimide film, in which the electrolytically plated copper film has ~~at most~~ 1 to 200 protrusions having a diameter of 15 μm or more per 1 mm^2 on a surface thereof not facing the polyimide film, and the laminate has a peel strength of 1 kgf/cm or more and shows a peel strength of 0.6 kgf/cm or more after heating at 150° C for 24 hours.

2. (Original) The copper-clad laminate of claim 1, in which the copper-clad laminate has a continuous laminate having a width of 540 mm or more and the copper film has such uniform thickness in a width direction thereof that the thickness varies within at most ± 10% at least in a range of 80% of the width.

3. (Original) The copper-clad laminate of claim 1, in which the polyimide film has a surface facing the plated copper film, which has protrusions arranged to form a network of protrusions.

4. (Original) The copper-clad laminate of claim 1, in which the polyimide film is prepared from a biphenyltetracarboxylic compound and a diamine compound comprising 4,4'-diaminodiphenyl ether.

5. (Original) The copper-clad laminate of claim 1, in which the polyimide film comprises a high heat resistant aromatic polyimide core layer and a flexible aromatic polyimide surface layers, the latter flexible polyimide layers comprises polyimide having a flexible bonding in a molecular structure thereof.

6. (Original) The copper-clad laminate of claim 1, in which at least two deposited metal layers are placed between the polyimide film and the plated copper film, and the plated copper film and the deposited metal layers have a total thickness in the range of 1

to 20 μm.

7. (Original) The copper-clad laminate of claim 1, in which the polyimide film has the plated copper layer on one surface side thereof and a heat conductive deposited metal or ceramic layer on another surface side thereof.

8. (Original) The copper-clad laminate of claim 1, in which the polyimide film has the plated copper layer on both surface side thereof.

9. (Original) The copper-clad laminate of claim 1, which shows a peel strength of 0.6 kgf/cm or more after PCT processing which is performed at 121° C for 168 hours under the conditions of 2 atm. and RH 100%.

10. (Original) The copper-clad laminate of claim 1, in which the plated copper layer has 0 to 200 protrusions per 1 mm^2 which have a diameter of 15 to 1,000 μm.

Claim 11 (Canceled)

12. (Original) The copper-clad laminate of claim 1, in which the plated copper layer has 0 to 50 protrusions per 1 mm^2 which have a diameter of more than 15 μm.

13. (Original) A process for preparing a copper-clad laminate of claim 1, comprising the steps of:

preparing a polyimide film having a combination of metal deposited underlying layer and a copper-deposited surface layer at least on one surface thereof; and

placing a copper film on the copper-deposited surface layer by electrolytically plating the surface of the copper-deposited layer by placing the polyimide film vertically in a plating solution.